



**矽普**

Siliup Semiconductor

**SP010N07AGNK**

100V N-Channel MOSFET

## Product Summary

<b>V<sub>(BR)DSS</sub></b>	<b>R<sub>DS(on)TYP</sub></b>	<b>I<sub>D</sub></b>
100V	6.2mΩ@10V	105A
	8mΩ@4.5V	

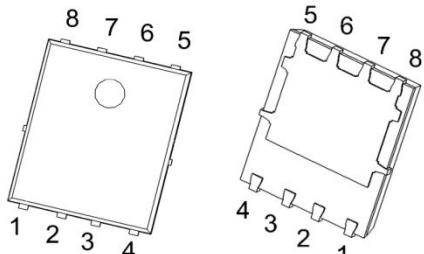
## Feature

- Low RDS(on) & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery

## Applications

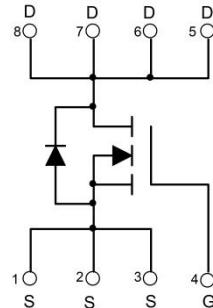
- Consumer electronic power supply
- Motor control Synchronous rectification
- Isolated DC/DC convertor
- Invertors

## Package

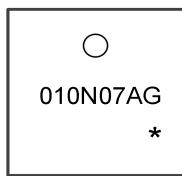


PDFN5X6-8L

## Circuit diagram



## Marking



010N07AG : Product code  
\* : Month code.



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**Absolute maximum ratings (Ta=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain source voltage	V <sub>DS</sub>	100	V
Gate source voltage	V <sub>GS</sub>	±20	V
Continuous drain current <sup>1)</sup> , TC=25 °C	I <sub>D</sub>	105	A
Pulsed drain current <sup>2)</sup> , TC=25 °C	I <sub>DM</sub>	420	A
Power dissipation <sup>3)</sup> , TC=25 °C	P <sub>D</sub>	178	W
Single pulsed avalanche energy <sup>4)</sup>	E <sub>AS</sub>	130	mJ
Thermal resistance, junction-case	R <sub>θJC</sub>	0.70	°C/W
Thermal resistance, junction-ambient	R <sub>θJA</sub>	62	°C/W
Operation and storage temperature	T <sub>stg</sub> , T <sub>j</sub>	-55 to 150	°C

**Electrical characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, ID=250 μA	100	-	-	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =100 V, V <sub>GS</sub> =0 V	-	-	1	μA
Gate-source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20 V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , ID=250 μA	1.0	1.7	2.5	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V, ID=12 A	-	6.2	7.8	mΩ
		V <sub>GS</sub> =4.5 V, ID=8 A	-	8	10.5	
<b>Dynamic Characteristics</b>						
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=1 MHz		3530		pF
Output capacitance	C <sub>oss</sub>			560		pF
Reverse transfer capacitance	C <sub>rss</sub>			9		pF
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, RG=2 Ω, ID=10 A		22.5		ns
Rise time	t <sub>r</sub>			8.6		ns
Turn-off delay time	t <sub>d(off)</sub>			66.6		ns
Fall time	t <sub>f</sub>			42.1		ns
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, ID=10 A		55.6		nC
Gate-source charge	Q <sub>gs</sub>			14.9		nC
Gate-drain charge	Q <sub>gd</sub>			11.2		nC
<b>Drain-Source Diode Characteristics</b>						
Diode forward voltage	V <sub>SD</sub>	IS=30 A, V <sub>GS</sub> =0 V			1.3	V
Reverse recovery time	t <sub>rr</sub>	VR=50 V, IS=10 A, di/dt=100 A/μs		67		ns
Reverse recovery charge	Q <sub>rr</sub>			160		nC
Peak reverse recovery current	I <sub>rrm</sub>			3.9		A

**Notes:**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) VDD=50 V, VGS=10 V, L=0.3 mH, , starting Tj=25 °C.



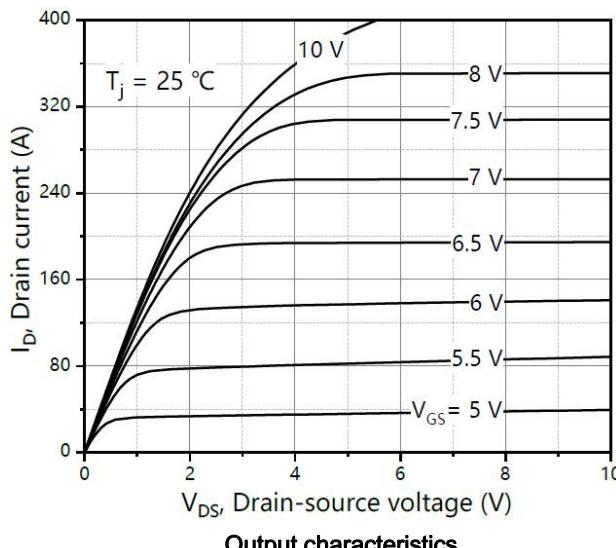
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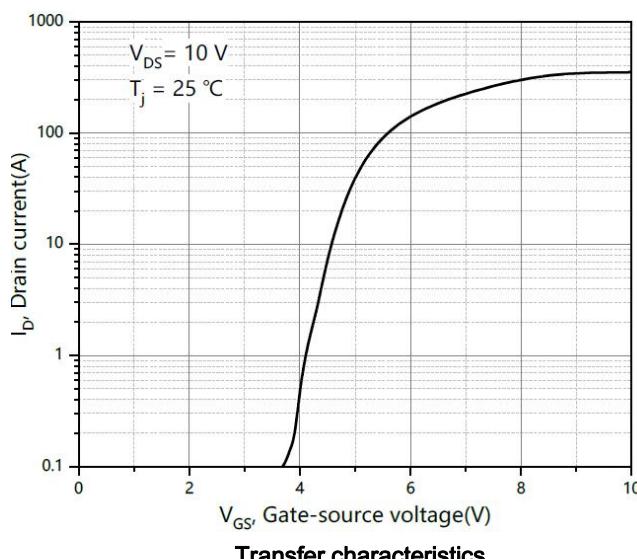
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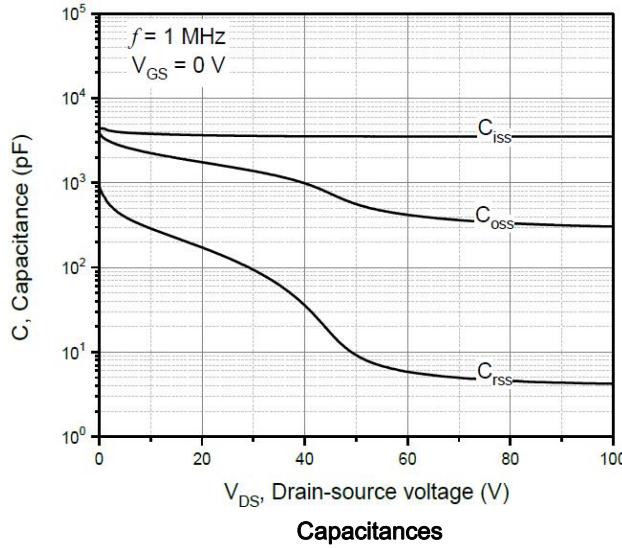
## Typical Characteristics



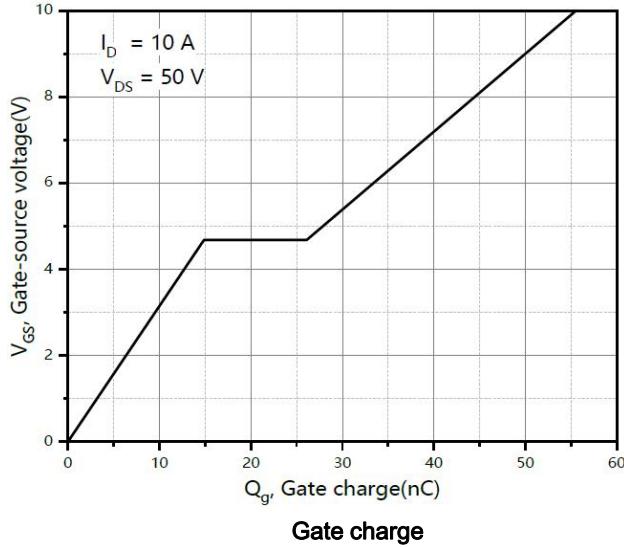
Output characteristics



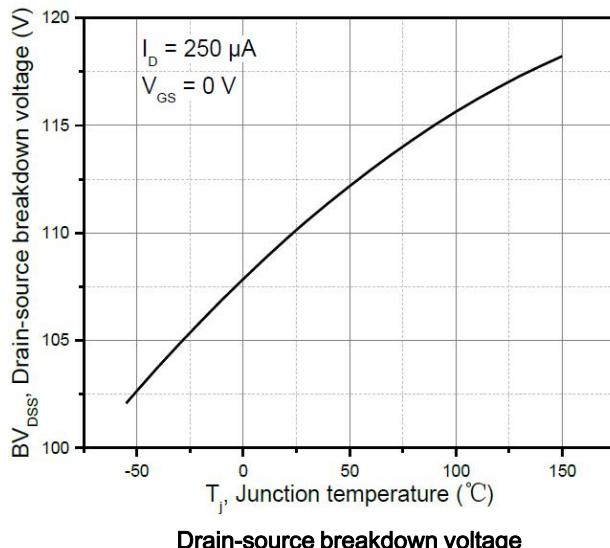
Transfer characteristics



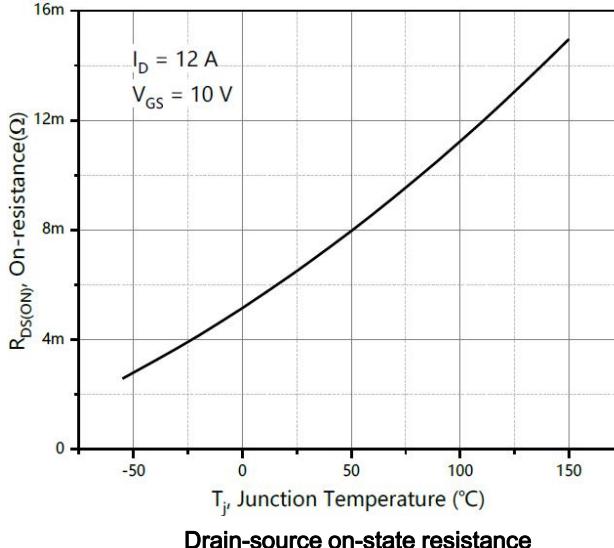
Capacitances



Gate charge



Drain-source breakdown voltage



Drain-source on-state resistance

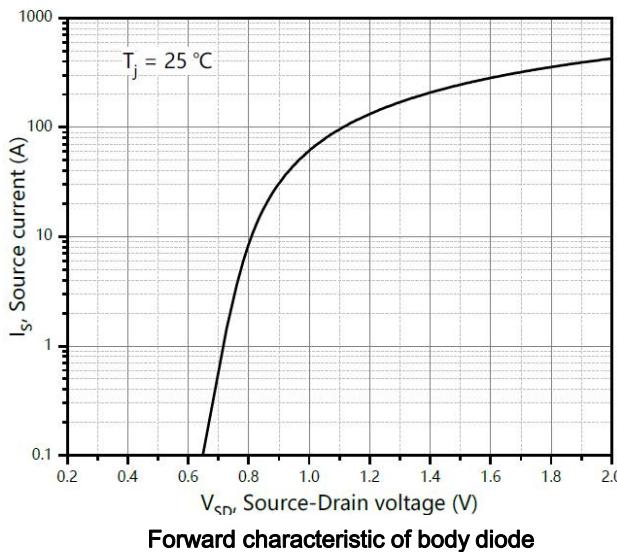


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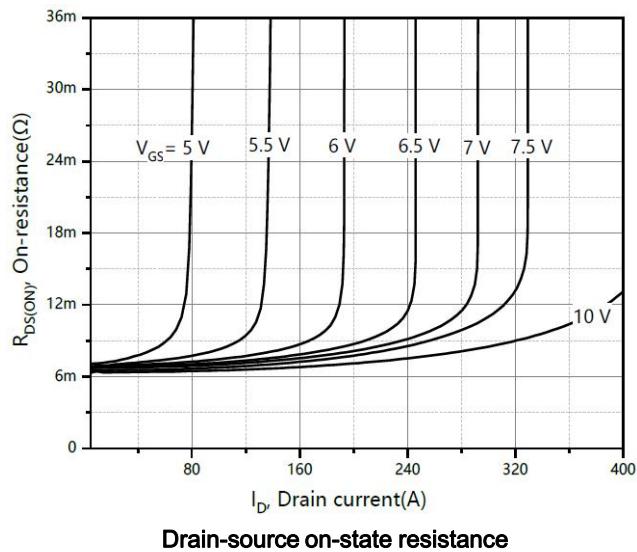
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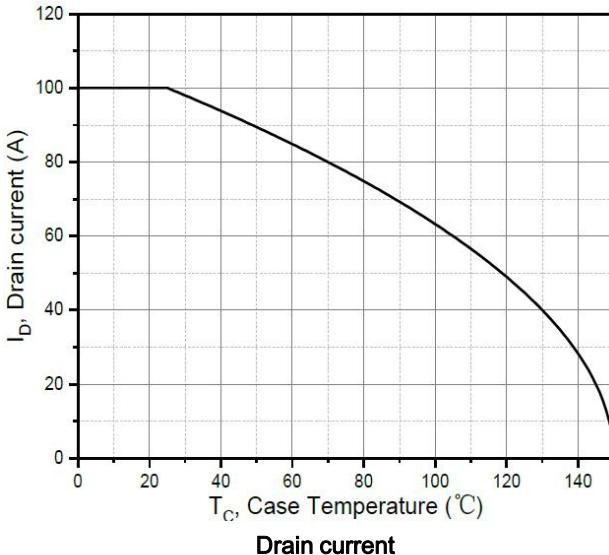
100V N-Channel MOSFET



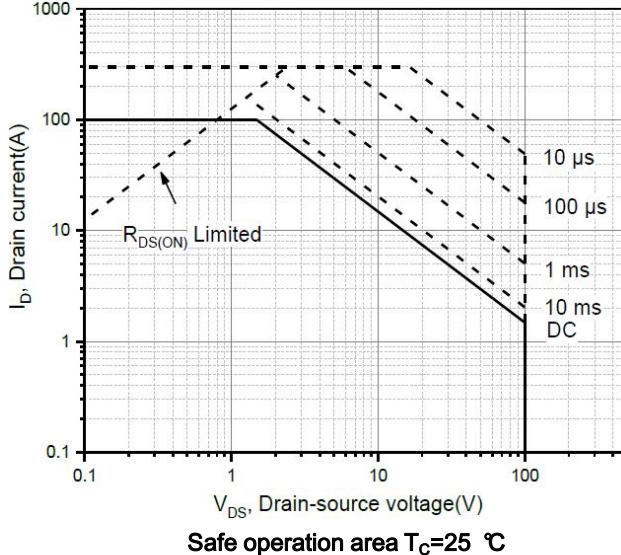
Forward characteristic of body diode



Drain-source on-state resistance



Drain current



Safe operation area  $T_c=25^\circ\text{C}$

## Test circuits and waveforms

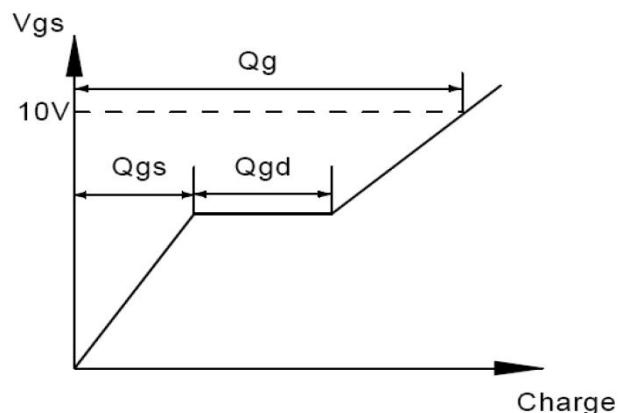
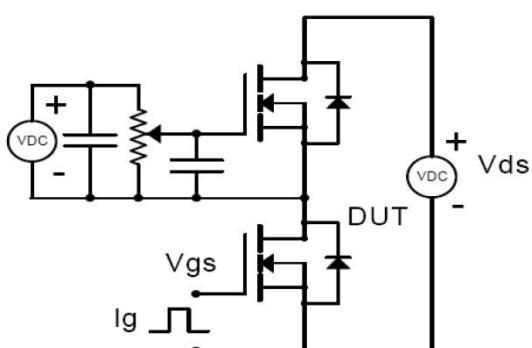


Figure 1, Gate charge test circuit &amp; waveform

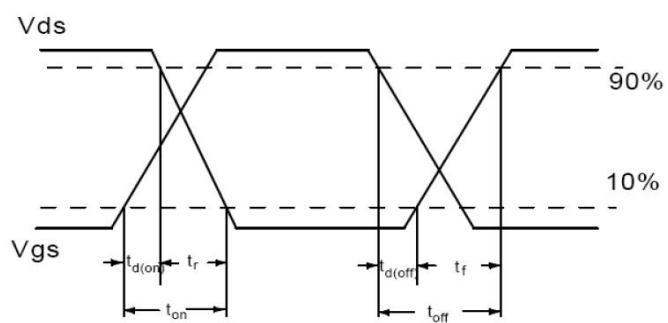
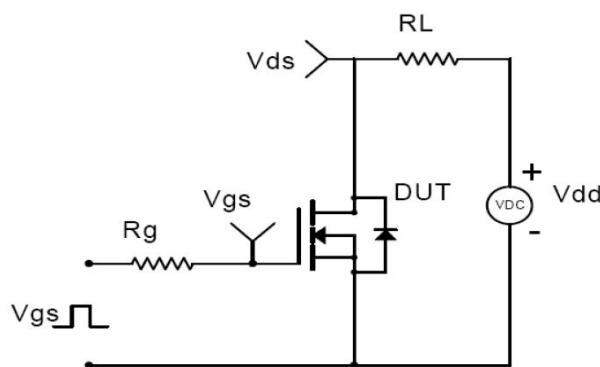


Figure 2, Switching time test circuit &amp; waveforms

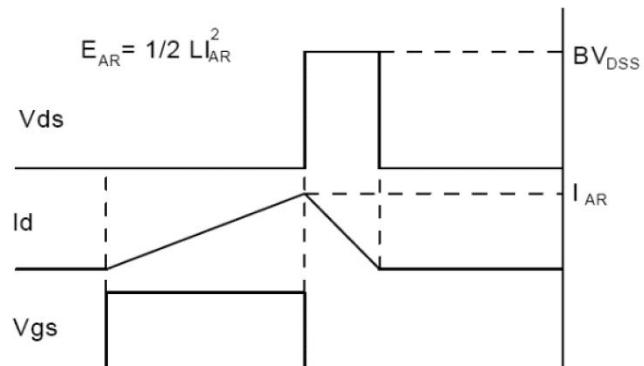
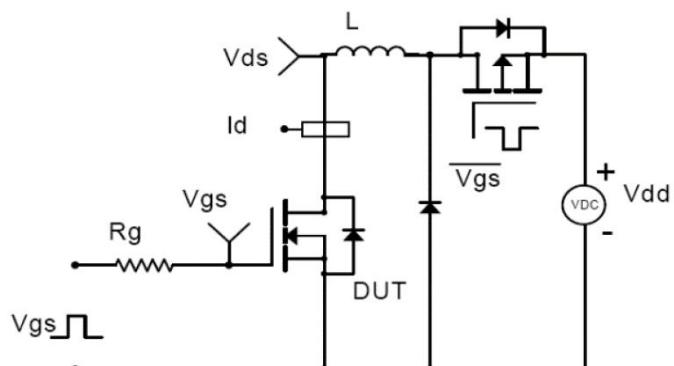


Figure 3, Unclamped inductive switching (UIS) test circuit &amp; waveforms

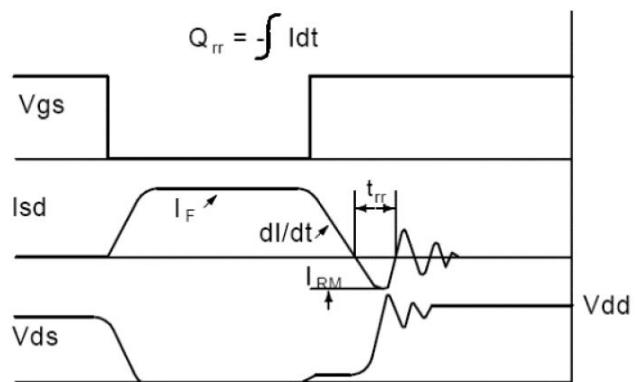
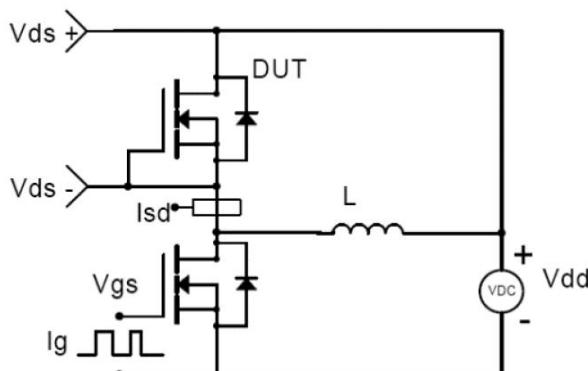


Figure 4, Diode reverse recovery test circuit &amp; waveforms



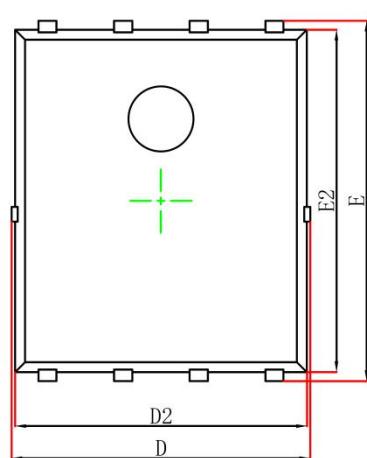
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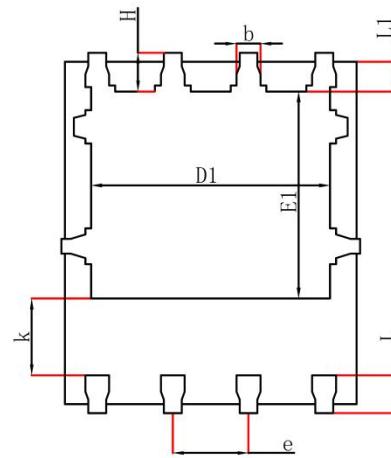
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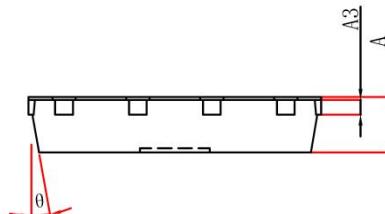
### PDFN5X6-8L Package Information



Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°